

# FGW50N65WD

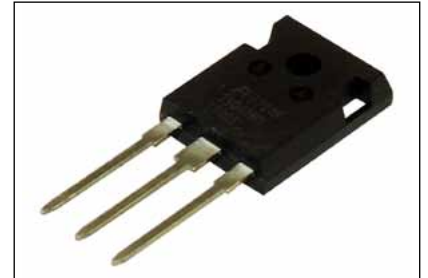
## Discrete IGBT (High-Speed W series) 650V / 50A

### ■ Features

- Low power loss
- Low switching surge and noise
- High reliability, high ruggedness (RBSOA, SCSOA etc.)

### ■ Applications

- Uninterruptible power supply
- PV Power conditioner
- Inverter welding machine



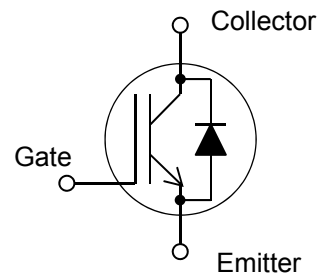
### ■ Maximum Ratings and Characteristics

#### ● Absolute Maximum Ratings (at T<sub>c</sub>=25°C unless otherwise specified)

Items	Symbols	Characteristics	Units	Remarks
Collector-Emitter Voltage	V <sub>CEs</sub>	650	V	
Gate-Emitter Voltage	V <sub>GES</sub>	±20	V	T <sub>p</sub> <1μs
Transient Gate-Emitter Voltage		±30		
DC Collector Current	I <sub>C@25</sub>	70	A	T <sub>c</sub> =25°C
	I <sub>C@100</sub>	50	A	T <sub>c</sub> =100°C
Pulsed Collector Current	I <sub>CP</sub>	200	A	Note *1
Turn-Off Safe Operating Area	-	200	A	V <sub>CE</sub> ≤650V T <sub>p</sub> ≤175°C
Diode Forward Current	I <sub>F@25</sub>	38	A	
	I <sub>F@100</sub>	25	A	
Diode Pulsed Current	I <sub>FP</sub>	200	A	Note *1
IGBT Max. Power Dissipation	P <sub>D,IGBT</sub>	190	W	T <sub>c</sub> =25°C
FWD Max. Power Dissipation	P <sub>D,FWD</sub>	95	W	T <sub>c</sub> =25°C
Operating Junction Temperature	T <sub>j</sub>	-40 ~ +175	°C	
Storage Temperature	T <sub>stg</sub>	-55 ~ +175	°C	

Note \*1 : Pulse width limited by T<sub>jmax</sub>.

### ■ Equivalent circuit



#### ● Electrical characteristics (at T<sub>j</sub>= 25°C unless otherwise specified)

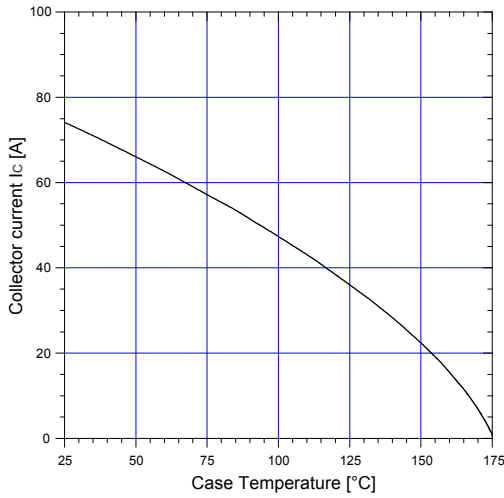
Description	Symbols	Conditions	Characteristics			Units
			min.	typ.	max.	
Zero Gate Voltage Collector Current	I <sub>CEs</sub>	V <sub>CE</sub> = 650V, V <sub>GE</sub> = 0V	T <sub>j</sub> =25°C -	T <sub>j</sub> =25°C -	T <sub>j</sub> =25°C 250	μA
Gate-Emitter Leakage Current	I <sub>GES</sub>	V <sub>CE</sub> = 0V, V <sub>GE</sub> = ±20V	-	-	2	mA
Gate-Emitter Threshold Voltage	V <sub>GE(th)</sub>	V <sub>CE</sub> = 20V, I <sub>C</sub> = 50mA	-	-	200	nA
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	V <sub>GE</sub> = 15V, I <sub>C</sub> = 50A	T <sub>j</sub> =25°C 1.40	T <sub>j</sub> =25°C 1.80	T <sub>j</sub> =25°C 2.20	V
			T <sub>j</sub> =125°C -	T <sub>j</sub> =125°C 2.05	T <sub>j</sub> =125°C -	
			T <sub>j</sub> =175°C -	T <sub>j</sub> =175°C 2.10	T <sub>j</sub> =175°C -	
Input Capacitance	C <sub>ies</sub>	V <sub>CE</sub> =25V	1830	3650	5480	pF
Output Capacitance	C <sub>oes</sub>	V <sub>GE</sub> =0V	103	105	208	
Reverse Transfer Capacitance	C <sub>res</sub>	f=1MHz	40	80	120	
Gate Charge	Q <sub>G</sub>	V <sub>CC</sub> = 520V I <sub>C</sub> = 50A V <sub>GE</sub> = 15V	108	215	323	nC
Turn-On Delay Time	t <sub>d(on)</sub>	T <sub>j</sub> = 25°C, V <sub>CC</sub> = 400V I <sub>C</sub> = 25A, V <sub>GE</sub> = 15V R <sub>G</sub> = 10Ω, L = 500μH Energy loss include "tail" and FWD reverse recovery.	14	27	41	ns
Rise Time	t <sub>r</sub>		16	32	48	
Turn-Off Delay Time	t <sub>d(off)</sub>		120	240	360	
Fall Time	t <sub>f</sub>		30	60	90	
Turn-On Energy	E <sub>on</sub>		0.21	0.42	0.63	
Turn-Off Energy	E <sub>off</sub>	0.23	0.46	0.69	mJ	
Turn-On Delay Time	t <sub>d(on)</sub>	T <sub>j</sub> = 150°C, V <sub>CC</sub> = 400V I <sub>C</sub> = 25A, V <sub>GE</sub> = 15V R <sub>G</sub> = 10Ω, L = 500μH Energy loss include "tail" and FWD reverse recovery.	14	27	41	ns
Rise Time	t <sub>r</sub>		16	32	48	
Turn-Off Delay Time	t <sub>d(off)</sub>		133	265	398	
Fall Time	t <sub>f</sub>		27	54	81	
Turn-On Energy	E <sub>on</sub>		0.35	0.70	1.05	
Turn-Off Energy	E <sub>off</sub>	0.27	0.54	0.81	mJ	
Forward Voltage Drop	V <sub>F</sub>	I <sub>F</sub> =25A	T <sub>j</sub> =25°C 1.8	T <sub>j</sub> =25°C 2.5	T <sub>j</sub> =25°C 3.2	V
			T <sub>j</sub> =125°C -	T <sub>j</sub> =125°C 1.9	T <sub>j</sub> =125°C -	V
			T <sub>j</sub> =175°C -	T <sub>j</sub> =175°C 1.7	T <sub>j</sub> =175°C -	V
Diode Reverse Recovery Time	t <sub>rr</sub>	V <sub>CC</sub> =400V, I <sub>F</sub> =25A	35	70	105	ns
Diode Reverse Recovery Charge	Q <sub>rr</sub>	-di <sub>F</sub> /dt=500A/μs, T <sub>j</sub> =25°C	0.16	0.32	0.48	μC
Diode Reverse Recovery Time	t <sub>rr</sub>	V <sub>CC</sub> =400V, I <sub>F</sub> =25A	48	95	143	ns
Diode Reverse Recovery Charge	Q <sub>rr</sub>	-di <sub>F</sub> /dt=500A/μs, T <sub>j</sub> =150°C	0.44	0.88	1.32	μC

## ● Thermal resistance characteristics

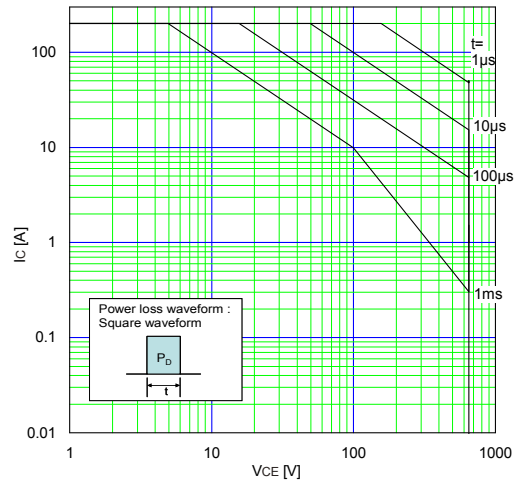
Items	Symbols	Conditions	Characteristics			Units
			min.	typ.	max.	
Thermal Resistance, Junction-Ambient	$R_{th(j-a)}$	-	-	-	50	°C/W
Thermal Resistance, IGBT Junction to Case	$R_{th(j-c)}_{IGBT}$	-	-	-	0.781	
Thermal Resistance, FWD Junction to Case	$R_{th(j-c)}_{FWD}$	-	-	-	1.563	

**Characteristics (Representative)**

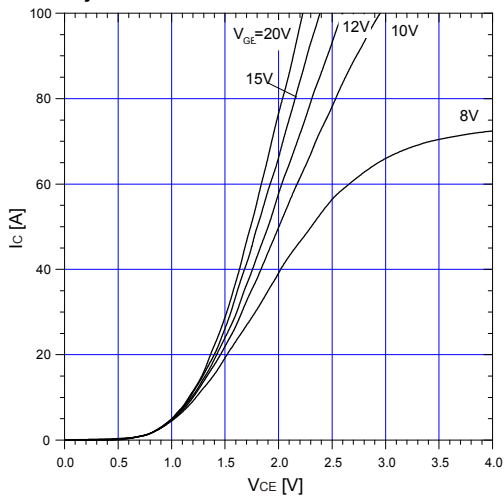
**Graph.1**  
DC Collector Current vs  $T_c$   
 $V_{GE} \geq +15V, T_j \leq 175^\circ C$



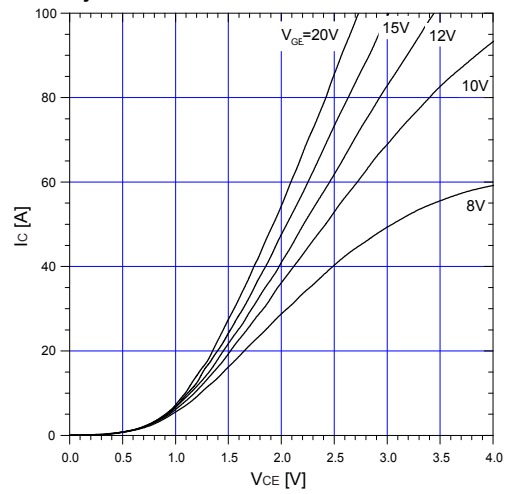
**Graph.2**  
SOA  
Duty=0(Single pulse),  $T_c=25^\circ C$



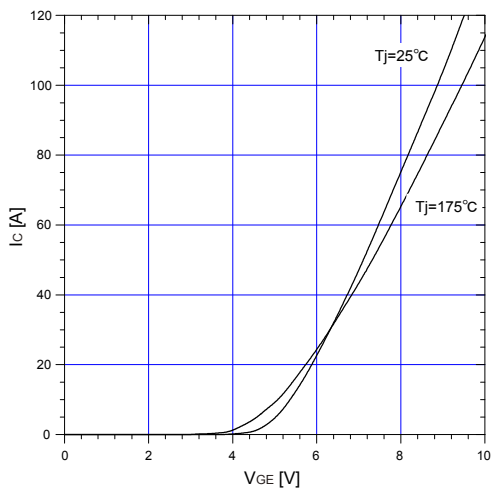
**Graph.3**  
Typical Output Characteristics ( $V_{CE}-I_c$ )  
 $T_j=25^\circ C$



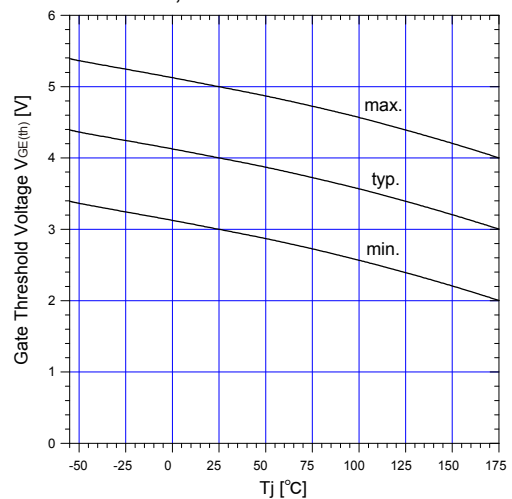
**Graph.4**  
Typical Output Characteristics ( $V_{CE}-I_c$ )  
 $T_j=175^\circ C$



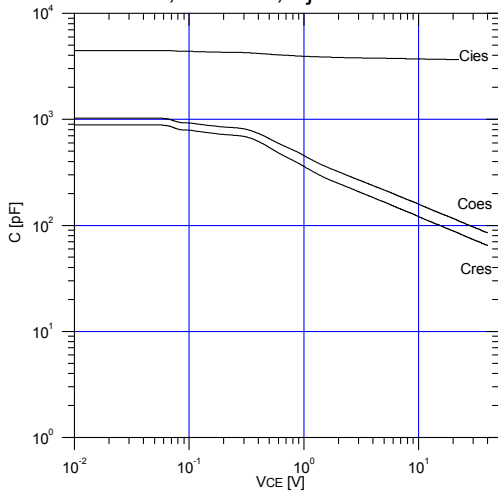
**Graph.5**  
Typical Transfer Characteristics  
 $V_{CE}=10V$



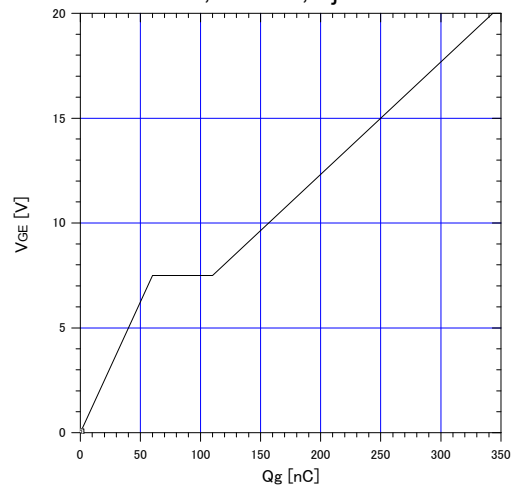
**Graph.6**  
Gate Threshold Voltage vs.  $T_j$   
 $I_c=50mA, V_{CE}=20V$



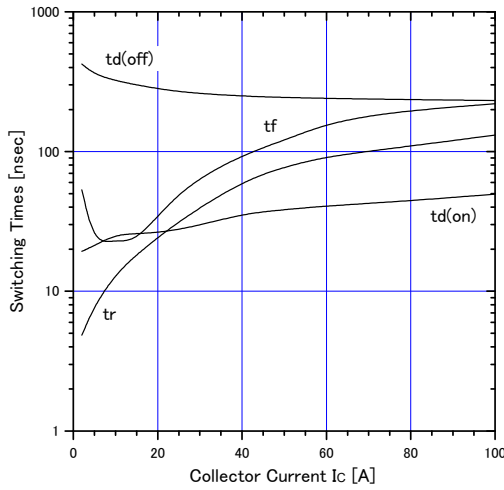
Graph.7  
Typical Capacitance  
 $V_{GE}=0V, f=1MHz, T_j=25^{\circ}C$



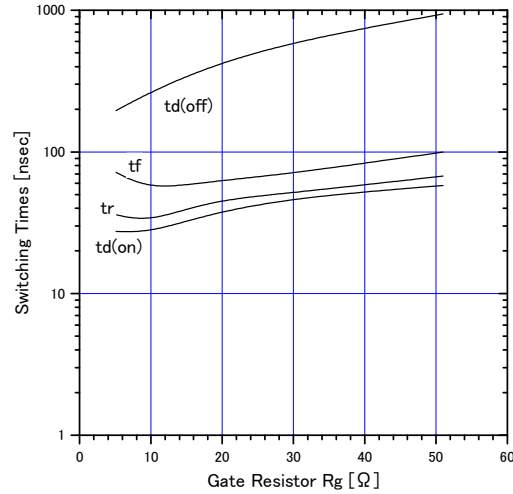
Graph.8  
Typical Gate Charge  
 $V_{CC}=520V, I_c=50A, T_j=25^{\circ}C$



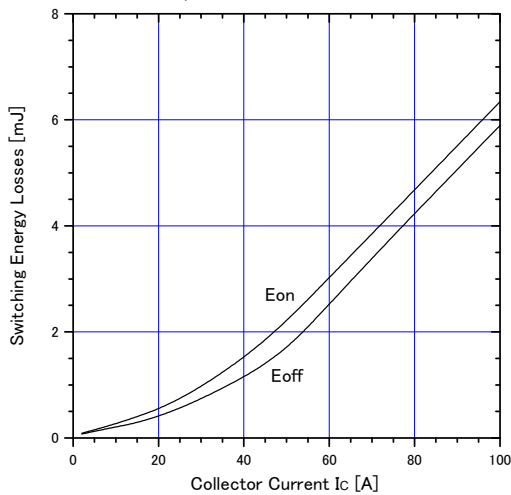
Graph.9  
Typical switching time vs. Ic  
 $T_j=150^{\circ}C, V_{CC}=400V, L=500\mu H$   
 $V_{GE}=15V, R_G=10\Omega$



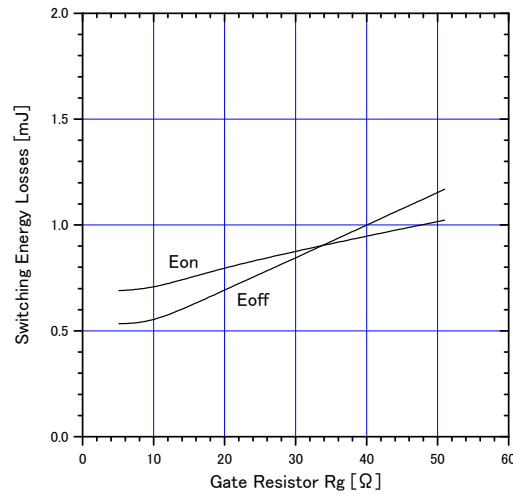
Graph.10  
Typical switching time vs. Rg  
 $T_j=150^{\circ}C, V_{CC}=400V, I_c=25A, L=500\mu H$   
 $V_{GE}=15V$



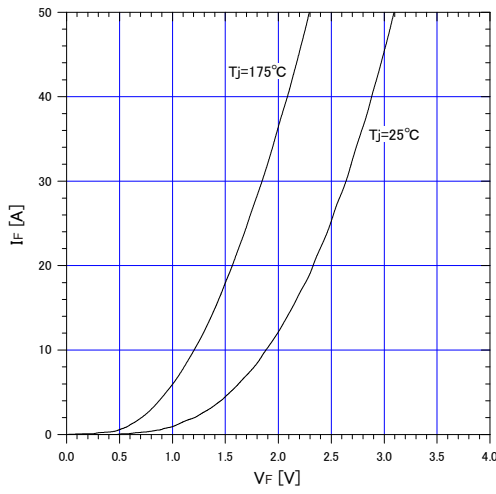
Graph.11  
Typical switching losses vs. Ic  
 $T_j=150^{\circ}C, V_{CC}=400V, L=500\mu H$   
 $V_{GE}=15V, R_G=10\Omega$



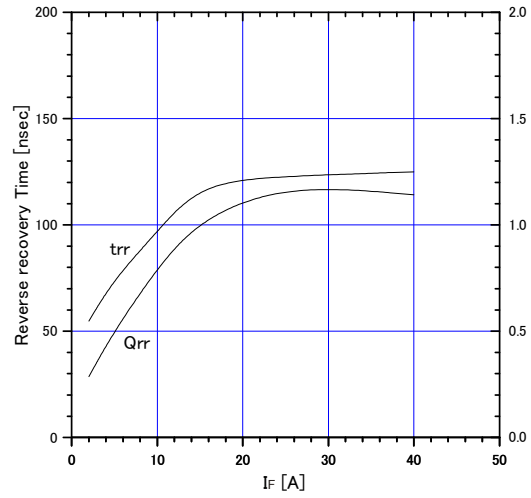
Graph.12  
Typical switching losses vs. Rg  
 $T_j=150^{\circ}C, V_{CC}=400V, I_c=25A, L=500\mu H$   
 $V_{GE}=15V$



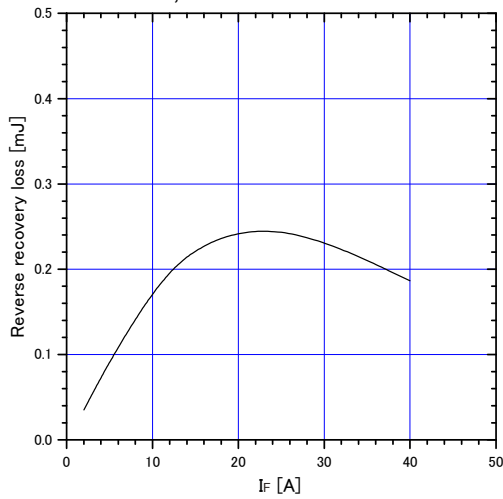
Graph.13  
FWD Forward voltage drop ( $V_F$ - $I_F$ )



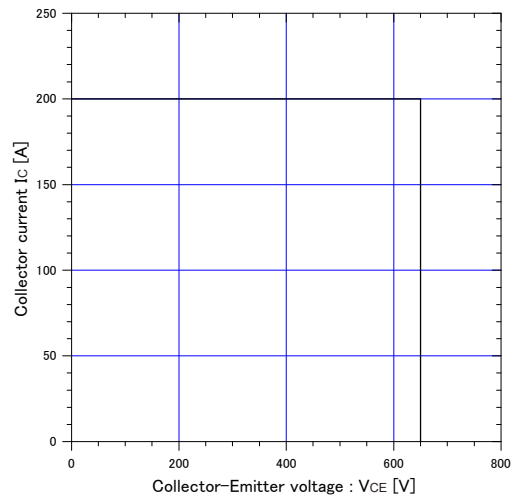
Graph.14  
Typical reverse recovery characteristics vs.  $I_F$   
 $T_j=150^\circ\text{C}$ ,  $V_{cc}=400\text{V}$ ,  $L=500\mu\text{H}$   
 $V_{GE}=15\text{V}$ ,  $R_G=10\Omega$



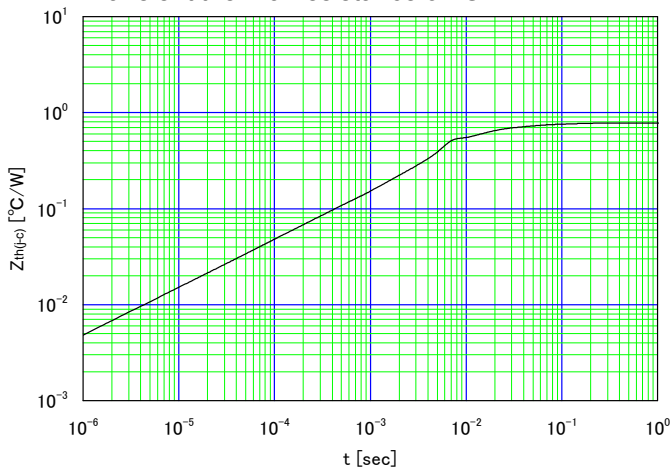
Graph.15  
Typical reverse recovery loss vs.  $I_F$   
 $T_j=150^\circ\text{C}$ ,  $V_{cc}=400\text{V}$ ,  $L=500\mu\text{H}$   
 $V_{GE}=15\text{V}$ ,  $R_G=10$



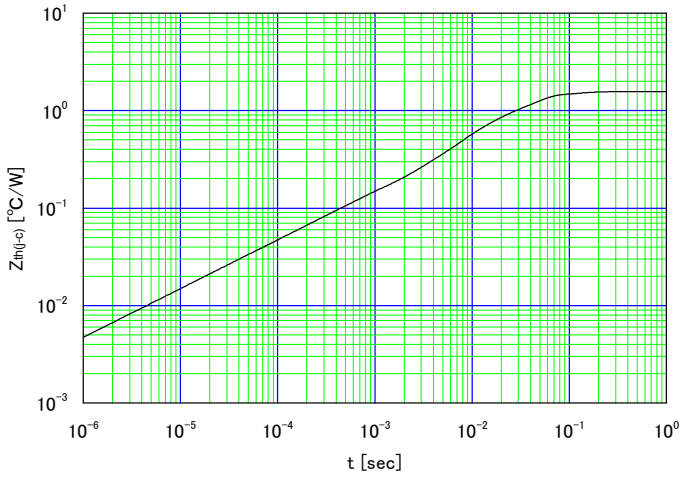
Graph.16  
Reverse biased Safe Operating Area  
 $T_j \leq 175^\circ\text{C}$ ,  $V_{GE}=+15\text{V}/0\text{V}$ ,  $R_G=10\Omega$



Graph.17  
Transient thermal resistance of IGBT

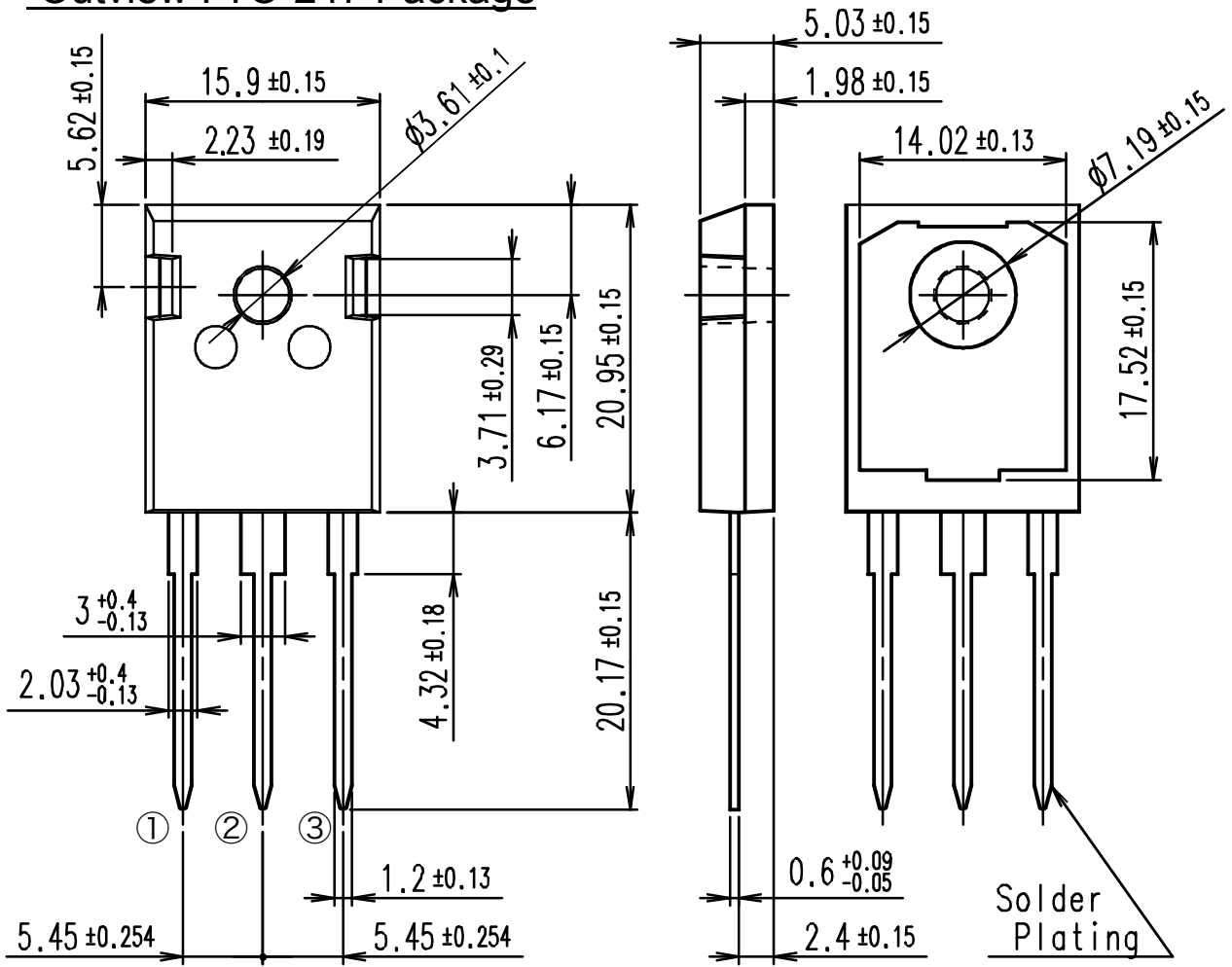


Graph.18  
Transient thermal resistance of FWD



■ Outline Drawings, mm

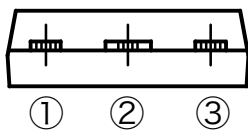
Outview : TO-247 Package



CONNECTION

- ① GATE
- ② COLLECTOR
- ③ EMITTER

DIMENSIONS ARE IN MILLIMETERS.



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  - Machine tools
  - Audiovisual equipment
  - Electrical home appliances
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  - Safety devices
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